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4					HEATSINK/M	DUNTING PLAN PCB SEALING	G			DATE 10.07.2018 4
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				INSTALLATIO	COMPONEI INDEX PAR	Т		TYPE MATERI		
				INGTALLATIO	2 C16			Lens PC Seal Silico		
					PRODUCT S				.EI	DiL®
F	www.ledil.com	ing from a product specific 3D			Plastic moulding ge according to DIN 16 if not otherwise sh Silicone moulding g according to ISO 33 and applies if not the drawing.	901-130 and applies own in the drawing. eneral tolerances 02-1 Class M3 otherwise shown in	FIRST ANGLE	of cop dis per	rmission from	may not be I ise out prior written LEDiL Oy.
	www.ledil.com	s about installation please see	e LEDiL Installation Guide on		SCALE	1:1	WEIGHT -		A3 SHE	ET 1/1
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